

WHAT IS CLAIMED IS:

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1. A logic emulation module comprising:
 - a plurality of programmable LSIs capable of programming logic;
 - a plurality of switching LSIs capable of programming connections;
 - connectors for electrical connection to entities external to the module;
 - a board on which to mount said plurality of programmable LSIs, said plurality of switching LSIs and said connectors; and
 - wiring furnished on said board for carrying data during emulation;
 - wherein said wiring at least includes lines for directly coupling said connectors to said programmable LSIs and lines for linking said connectors to said programmable LSIs by way of said switching LSIs.
2. A logic emulation module according to claim 1, further comprising lines for connecting each programmable LSI to said plurality of switching LSIs.
3. A logic emulation module according to claim 1, further comprising lines for connecting each switching LSI to said plurality of programmable LSIs.

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of said board.

9. A logic emulation module according to claim 8, wherein, of pins on said connectors, at least those for power supply and ground lines are positioned in opposite fashion on said face and said back of said board and connected by use of through-holes.

10. A logic emulation board comprising:
a board;
connectors for connection to logic emulation modules mounted on said board; and
terminal lands for supporting an LSI targeted for development and mounted on said board.

11. A logic emulation board according to claim 10, further comprising board wiring for connecting pins of said connectors to said terminal lands on a one-to-one basis.

12. A logic emulation device made of a logic emulation board and a logic emulation module connected to said logic emulation board;

wherein said logic emulation board includes:

a board;

connectors for connection to said logic emulation

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module mounted on said board; and

terminal lands for supporting an LSI targeted for development and mounted on said board; and

wherein said logic emulation module includes:

a plurality of programmable LSIs capable of programming logic;

a plurality of switching LSIs capable of programming connections;

connectors for electrical connection to said logic emulation board;

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a board on which to mount said plurality of programmable LSIs, said plurality of switching LSIs, and said connectors; and

wiring furnished on said board and carrying data during emulation, said wiring at least including lines for directly coupling said connectors to said programmable LSIs and lines for linking said connectors to said programmable LSIs by way of said switching LSIs.

13. A logic module on a board, at least on one side of said board comprising:

a plurality of programmable logic elements;

connectors for exchanging input and output signals to and from said plurality of programmable logic elements; and

switching elements for controlling connections

of said logic board includes:

a plurality of programmable logic elements;

a first connector for exchanging input and output signals to and from said logic elements; and

switching elements for controlling connections between said plurality of programmable logic elements;

wherein said logic board includes:

a plurality of terminal lands for connecting terminals of said integrated circuits to said logic board; and

a second connector for connecting said logic module to peripheral portions of said logic board where said integrated circuits are mounted;

wherein said plurality of programmable logic elements are connected to either said first connector or to said switching elements;

wherein logic data for logic verification are programmed in said plurality of programmable logic elements; and

wherein said terminal lands and terminals of said second connector are linked on a one-to-one basis.

18. An integrated circuit having undergone logic verification by a logic verification system connecting a logic module implementing logic of said integrated circuit

large-scale integrated circuits to said switching large-scale integrated circuits in series.

22. A multi-chip module having a plurality of integrated circuits mounted on a board, said multi-chip module comprising:

radiation plates for covering said integrated circuits;

metal spacers; and

a heat conduction sheet interposed between said integrated circuits on the one hand and said radiation plates on the other hand.

23. A multi-chip module according to claim 22, wherein said integrated circuits are mounted on a first and a second side of said board;

wherein said first and said second side of said board are provided with said radiation plates;

wherein one edge of a flexible heat conduction sheet is attached to the radiation plates on said first side of said board; and

wherein another edge of said flexible heat conduction sheet is attached to the radiation plates on said second side of said board.

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